High Voltage 3-Phase Motor Driver

Features and Benefits

- Built-in pre-drive IC
- IGBT power element
- CMOS compatible input (3.3 to 5 V)
- High-side gate driver using bootstrap circuit or floating power supply
- Integrated Fast Recovery Diode (FRD) as freewheeling diode for each IGBT
- Built-in protection circuit for controlling power supply voltage drop
- Built-in overtemperature detection circuit (TD)
- 3-shunt configuration
- Output of fault signal during operation of protection circuit
- Output current 3 A
- Small SIP (SLA 24-pin)

Package: Power SIP

Not to scale

Description

The SLA6845MZ inverter power module (IPM) device provides a robust, highly-integrated solution for optimally controlling 3-phase motor power inverter systems and variable speed control systems used in energy-conserving designs to drive motors of residential and commercial appliances. These ICs take 230 VAC input voltage, and 3 A (continuous) output current. They can withstand voltages of up to 600 V (IGBT breakdown voltage).

The SLA6840M power package includes an IC with all of the necessary power elements (six IGBTs), pre-driver ICs (two), and freewheeling diodes (six), needed to configure the main circuit of an inverter. This enables the main circuit of the inverter to be configured with fewer external components than traditional designs.

Applications include residential white goods (home applications) and commercial appliance motor control:

- Air conditioner fan
- Refrigerator compressor
- Dishwasher pump

Functional Block Diagram

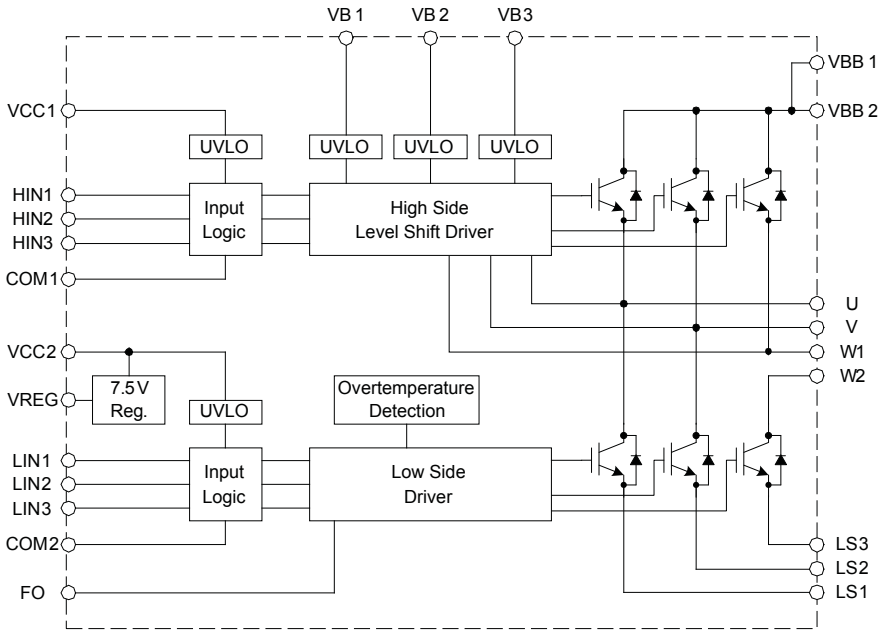


Figure 1. Driver block diagram.

Selection Guide

Part Number	Packing	IGBT Breakdown Voltage, V_{CES}(min) (V)	IGBT Saturation Voltage, $V_{CE(sat)}$(typ) (V)	Output Current	
				Continuous, I_O(max) (A)	Pulsed, I_{OP} (max) (A)
SLA6845MZ	18 pieces per tube	600	1.75	3	6

Absolute Maximum Ratings, valid at T_A = 25°C

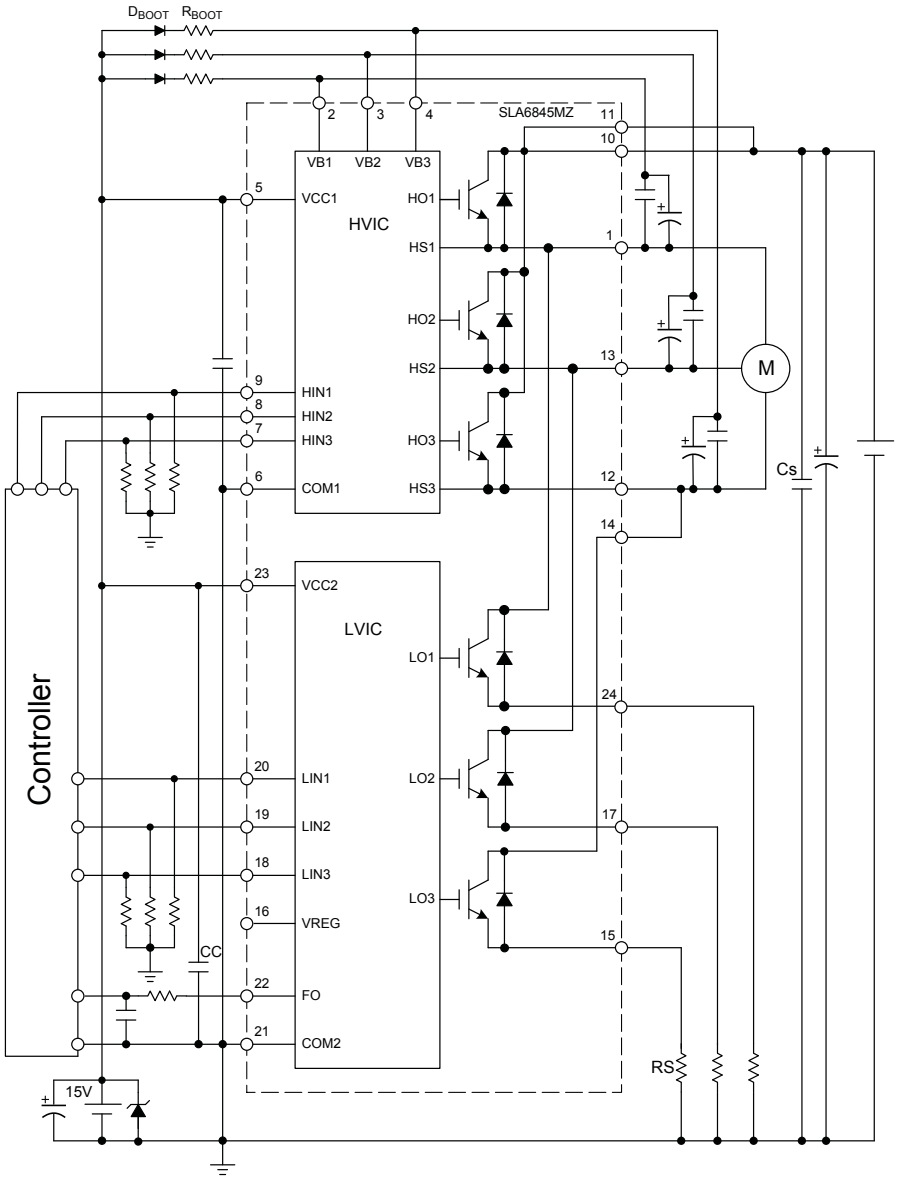
Characteristic	Symbol	Remarks	Rating	Unit
Main Supply Voltage	V_{BB}	Maximum voltage that can be applied between VBB and LSx continuously	450	V
Main Supply Voltage (Peak)	$V_{BB(surge)}$	Maximum voltage allowed between VBB and LSx, including transient switching noise. If surge voltages reach this rating, the snubber circuit should be improved so the voltage does not exceed this level.	500	V
IGBT Breakdown Voltage	V_{CES}		600	V
Logic Supply Voltage	V_{CC}	Between VCC and COM	20	V
Bootstrap Voltage	V_{BS}	Between VB and HS (U,V, and W phases)	20	V
Output Current, Continuous	I_O	T_C = 25°C	3	A
Output Current, Pulsed	I_{OP}	PW ≤ 100 µs	6	A
Output Current for Regulator	I_{REG}		35	mA
Input Voltage	V_{IN}		–0.5 to 7	V
Allowable Power Dissipation	P_D	T_C = 25°C, all elements operating	32	W
Thermal Resistance (Junction to Case)	$R_{\theta JC(I)}$	All elements operating (IGBT)	3.8	°C/W
	$R_{\theta JC(F)}$	All elements operating (FRD)	4.2	°C/W
Thermal Resistance (Junction to Ambient)	$R_{\theta JA}$	All elements operating (IGBT and FRD)	25	°C/W
Case Operating Temperature	T_{COP}		–20 to 100	°C
Junction Temperature (IGBT)	T_J		150	°C
Storage Temperature	T_{stg}		–40 to 150	°C

Recommended Operating Conditions

Characteristic	Symbol	Remarks	Min.	Typ.	Max.	Units
Main Supply Voltage	V_{BB}	Between VBB and LS, I_{BB} ≤ 2 A	–	300	450	V
Logic Supply Voltage	V_{CC}	Between VCC and COM	13.5	–	16.5	V
Shunt Resistor	R_S	LS1, LS2, LS3 to COM2	0.3	–	–	Ω
Dead Time	t_{dead}	Between LS1, LS2, LS3 and COM	1.5	–	–	µs
Overcurrent Protection (OCP) Response Time	t_{OCP}	No built-in OCP. If OCP required, implement using an external circuit. Measure t_{OCP} from overcurrent occurrence to shutdown command received on corresponding HINx or LINx terminal.	–	–	2.0	µs
Snubber Capacitor	C_S	Between VCC and COM. Use properly-rated film capacitor for voltage surge suppression.	0.01	–	0.1	µF
Junction Temperature	T_J		–	–	125	°C

All performance characteristics given are typical values for circuit or system baseline design only and are at the nominal operating voltage and an ambient temperature, T_A, of 25°C, unless otherwise stated.

Typical Application Diagram



NOTE:

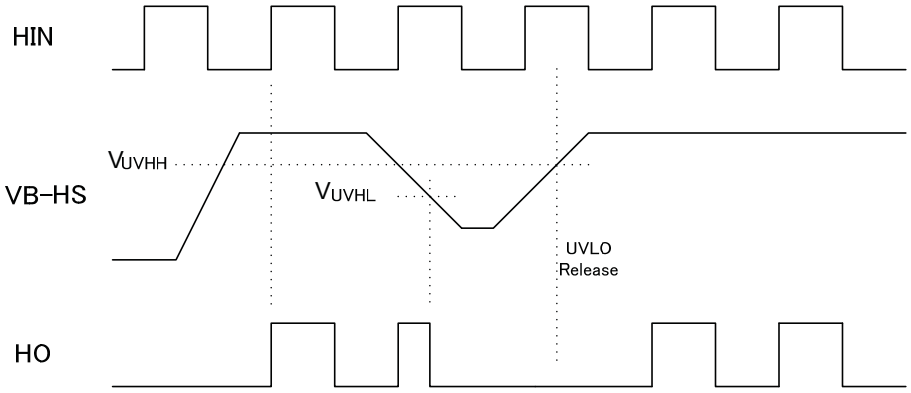
- All of the input pins are connected to GND with internal pull-down resistors rated at 100 kΩ, however, an external pull-down resistor may be required to secure stable condition of the inputs if high impedance conditions are applied to them.
- The external electrolytic capacitors should be placed as close to the IC as possible, in order to avoid malfunctions from external noise interference. Put a ceramic capacitor in parallel with the electrolytic capacitor if further reduction of noise susceptibility is necessary.

ELECTRICAL CHARACTERISTICS, valid at T_A=25°C, unless otherwise noted

Characteristics	Symbol	Conditions	Min	Typ	Max	Units
Logic Supply Voltage	V_{CC}	Between VCC and COM	13.5	15	16.5	V
Logic Supply Current	I_{CC}	V_{CC} = 15 V, V_{IN} = 5 V	–	4	6	mA
Input Voltage	V_{IH}	V_{CC} = 15 V, output on	–	2.0	2.5	V
	V_{IL}	V_{CC} = 15 V, output off	1.0	1.5	–	V
Input Voltage Hysteresis	V_{Ihys}	V_{CC} = 15 V	–	0.5	–	V
Input Current	I_{IH}	High side, V_{CC} = 15 V, V_{IN} = 5 V	–	50	100	µA
	I_{IL}	Low side, V_{CC} = 15 V, V_{IN} = 0 V	–	–	2	µA
Undervoltage Lockout	V_{UVHL}	High side, between VB and U, V, or W	9.0	10.0	11.0	V
	V_{UVHH}		9.5	10.5	11.5	V
	V_{UVHhys}	High side, hysteresis	–	0.5	–	V
	V_{UVLL}	Low side, between VCC and COM	10.0	11.0	12.0	V
	V_{UVLH}		10.5	11.5	12.5	V
	V_{UVLhys}	Low side, hysteresis	–	0.5	–	V
$-V_O$ for Output Voltage[1]	$-V_O$	Between U, V, or W and COM	–5	–	–	V
LS Negative Surge Voltage[2]	V_{LS}	Between LS1, LS2, or LS3 and COM	–5	–	5	V
FO Terminal Output Voltage	V_{FOL}	V_{CC} = 15 V, I_{FO} = –1 mA	0	–	1.0	V
	V_{FOH}	V_{CC} = 15 V, I_{FO} = –1.6 mA	4.0	–	5.5	V
Overtemperature Detection Activating and Releasing Temperature	T_{TDH}	V_{CC} = 15 V, no heatsink, I_{REG} = 0 mA	135	150	165	°C
	T_{TDL}		105	120	135	°C
	T_{TDhys}		–	30	–	°C
Output Voltage for Regulator	V_{REG}	I_{REG} = 0 to 35 mA	6.75	7.5	8.25	V
IGBT Breakdown Voltage	V_{CES}	V_{CC} = 15 V, I_C = 1 mA, V_{IN} = 0 V	600	–	–	V
IGBT Leakage Current	I_{CES}	V_{CC} = 15 V, V_{CE} = 600 V, V_{IN} = 0 V	–	–	1	mA
IGBT Saturation Voltage	$V_{CE(sat)}$	V_{CC} = 15 V, I_C = 3 A, V_{IN} = 5 V	–	1.75	2.1	V
Diode Forward Voltage	V_F	V_{CC} = 15 V, I_F = 3 A, V_{IN} = 0 V	–	1.65	2.0	V
Diode Recovery Time	t_{rr}	I_F = 3 A, di/dt = 100 A/µs	–	50	–	ns
Switching Time, High Side	$t_{dH(on)}$	V_{BB} = 300 V, V_{CC} = 15 V, I_C = 3 A, 0 V ≤ V_{IN} ≤ 5 V, inductive load	–	315	–	ns
	t_{rH}		–	50	–	ns
	$t_{dH(off)}$		–	375	–	ns
	t_{fH}		–	165	–	ns
Switching Time, Low Side	$t_{dL(on)}$		–	325	–	ns
	t_{rL}		–	60	–	ns
	$t_{dL(off)}$		–	400	–	ns
	t_{fL}		–	165	–	ns

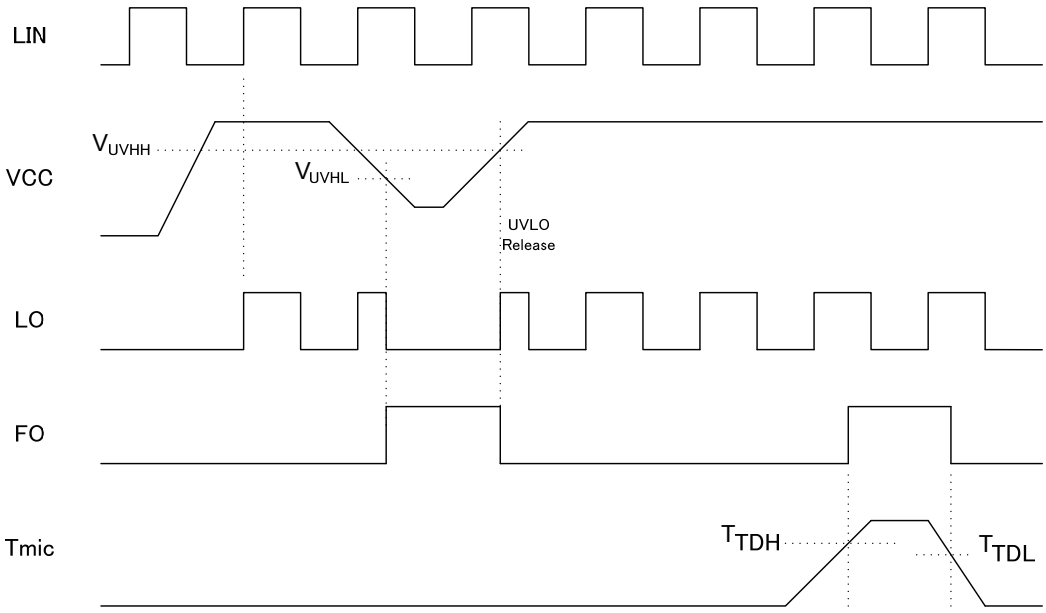
[1]Indicates normal operating range for the high-side driver IC.
[2]Indicates the allowable range assuming any transient surge <1 µs.

High-Side Driver Input/Output Timing Diagrams



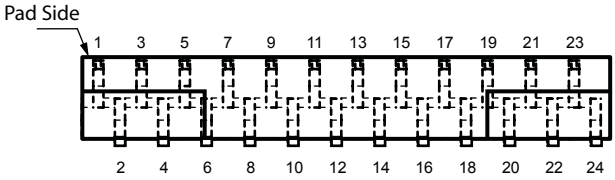
• High-side turn-on at next rising edge on HIN signal after UVLO release.
• FO output state does not change at high-side UVLO.

Low-Side Driver Input/Output Timing Diagrams



• Low-side turn-on in accordance with LIN signal level after UVLO release.
• FO output state goes high at low-side UVLO.

Pin-out Diagram



(Top View)

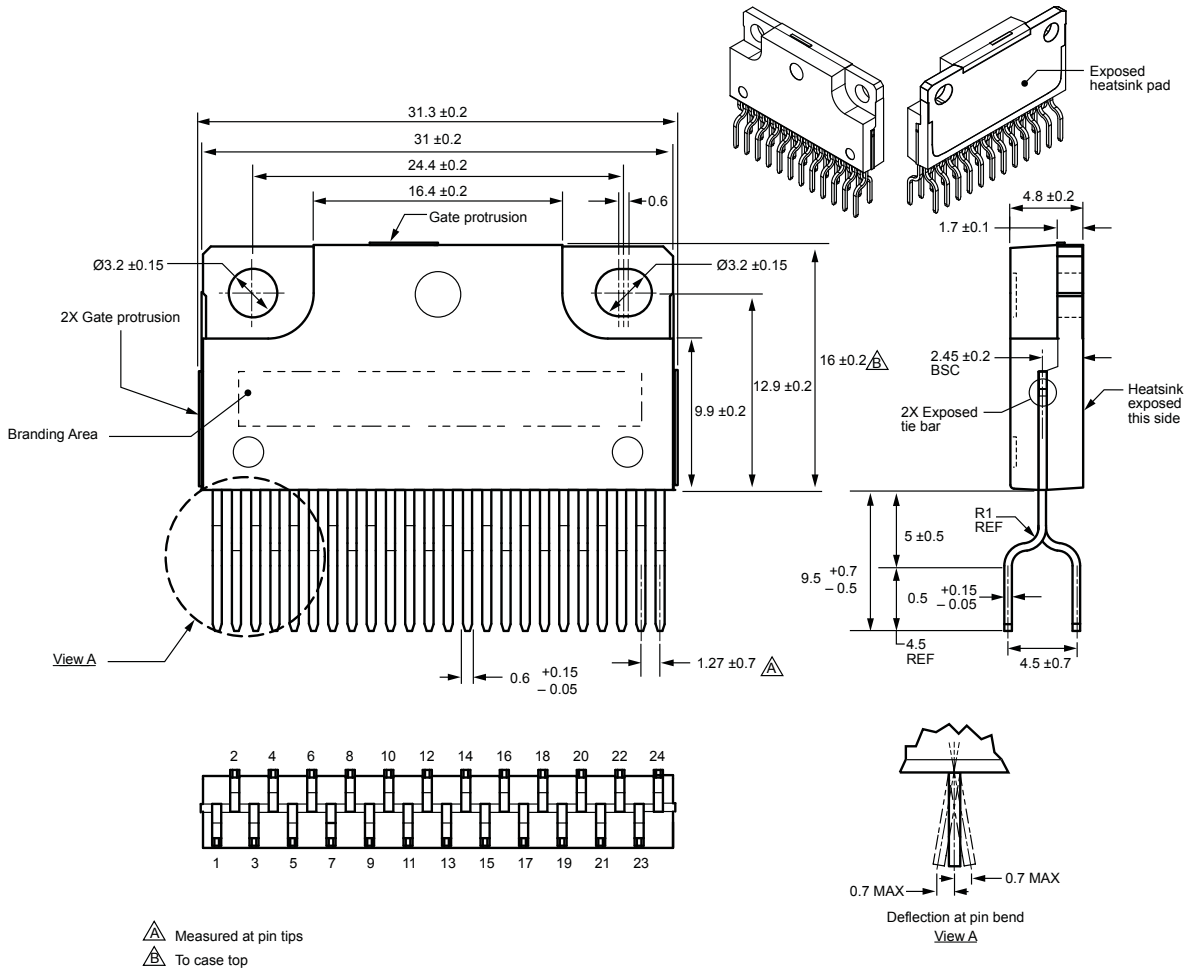
Terminal List Table

Number	Name	Function
1	U	Output of U phase
2	VB1	High side bootstrap terminal (U phase)
3	VB2	High side bootstrap terminal (V phase)
4	VB3	High side bootstrap terminal (W phase)
5	VCC1	High side logic supply voltage
6	COM1	High side logic GND terminal
7	HIN3	High side input terminal (W phase)
8	HIN2	High side input terminal (V phase)
9	HIN1	High side input terminal (U phase)
10	VBB1	Main supply voltage 1 (connect to VBB2 externally)
11	VBB2	Main supply voltage 2 (connect to VBB1 externally)
12	W1	Output of W phase (connect to W2 externally)
13	V	Output of V phase
14	W2	Output of W phase (connect to W1 externally)
15	LS3	Low side emitter terminal (W phase)
16	VREG	Internal regulator output terminal
17	LS2	Low side emitter terminal (V phase)
18	LIN3	Low side input terminal (W phase)
19	LIN2	Low side input terminal (V phase)
20	LIN1	Low side input terminal (U phase)
21	COM2	Low side GND terminal
22	FO	Overtemperature detection fault-signal output terminal
23	VCC2	Low side logic supply voltage
24	LS1	Low side source terminal (U phase)

Package Outline Drawing

Leadform 2171

Dual rows, 24 alternating pins; vertical case mounting; pin #1 on pad side



A Measured at pin tips
B To case top

Leadform: 2171
Terminal core material: Cu
Terminal plating: Ni
Recommended attachment: Solder dip (Sn-Ag-Cu)

Dimensions in millimeters
Branding codes (exact appearance at manufacturer discretion):
1st line, type: SLA6845M

2nd line, lot: *YMDDZ*
Where: Y is the last digit of the year of manufacture
M is the month (*1* to *9, O, N, D*)
DD is the date
Z represents the version, SLA6845MZ

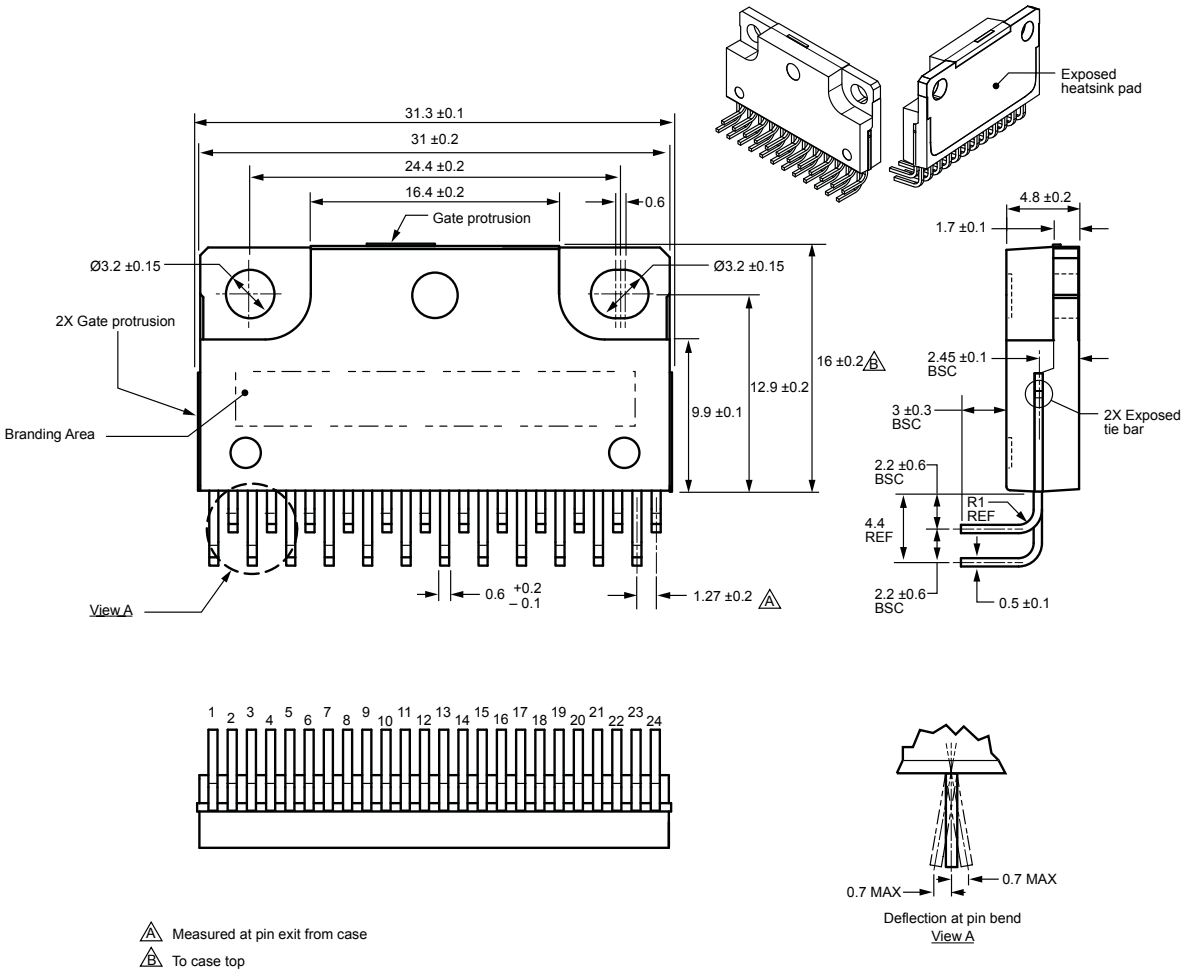
Leadframe plating Pb-free. Device composition complies with the RoHS directive.

Appearance: The body shall be clean and shall not bear any stain, rust or flaw.
Marking: The type number and lot number shall be clearly marked.

Package Outline Drawing

Leadform 2175

Dual rows, 24 alternating pins; pins bent 90° for horizontal case mounting; pin #1 in outer row



A Measured at pin exit from case

B To case top

Leadform: 2175
Terminal core material: Cu
Terminal plating: Ni
Recommended attachment: Solder dip (Sn-Ag-Cu)

Dimensions in millimeters

Branding codes (exact appearance at manufacturer discretion):
1st line, type: SLA6845M

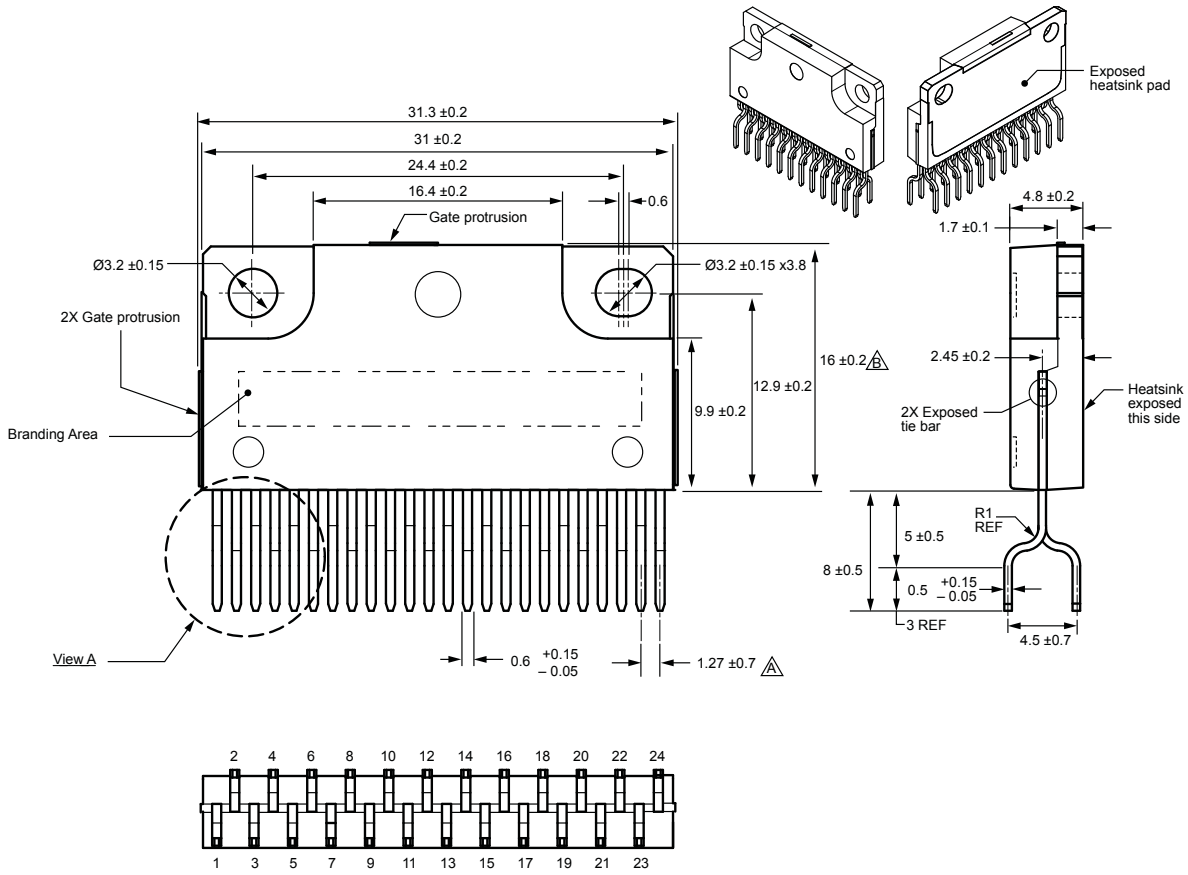
2nd line, lot: *YMDDZ*
Where: Y is the last digit of the year of manufacture
M is the month (*1* to *9*, *O*, *N*, *D*)
DD is the date
Z represents the version, SLA6845MZ

Leadframe plating Pb-free. Device composition complies with the RoHS directive.

Appearance: The body shall be clean and shall not bear any stain, rust or flaw.
Marking: The type number and lot number shall be clearly marked.

Package Outline Drawing
Leadform 2178

Dual rows, 24 alternating pins; vertical case mounting; pin #1 on pad side



A Measured at pin tips
B To case top

Leadform: 2178
Terminal core material: Cu
Terminal plating: Ni
Recommended attachment: Solder dip (Sn-Ag-Cu)

Dimensions in millimeters

Branding codes (exact appearance at manufacturer discretion):
1st line, type: SLA6845M

2nd line, lot: *YMDDZ*
Where: Y is the last digit of the year of manufacture
M is the month (*1* to *9*, *O*, *N*, *D*)
DD is the date
Z represents the version, SLA6845MZ

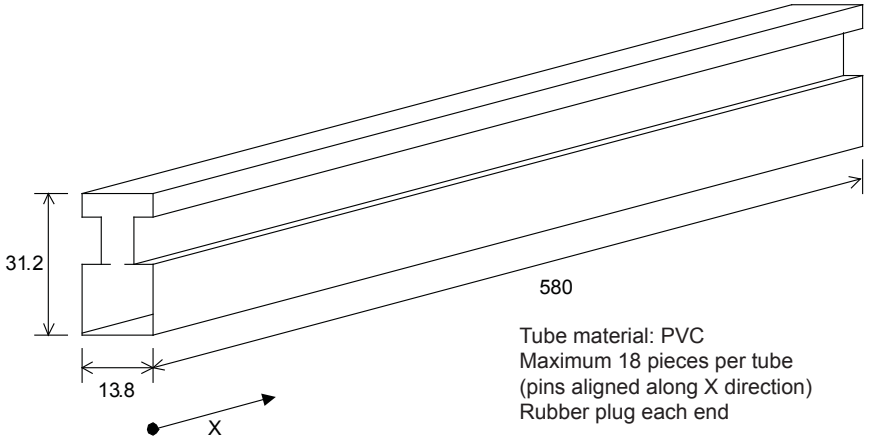
Leadframe plating Pb-free. Device composition complies with the RoHS directive.

Appearance: The body shall be clean and shall not bear any stain, rust or flaw.
Marking: The type number and lot number shall be clearly marked.

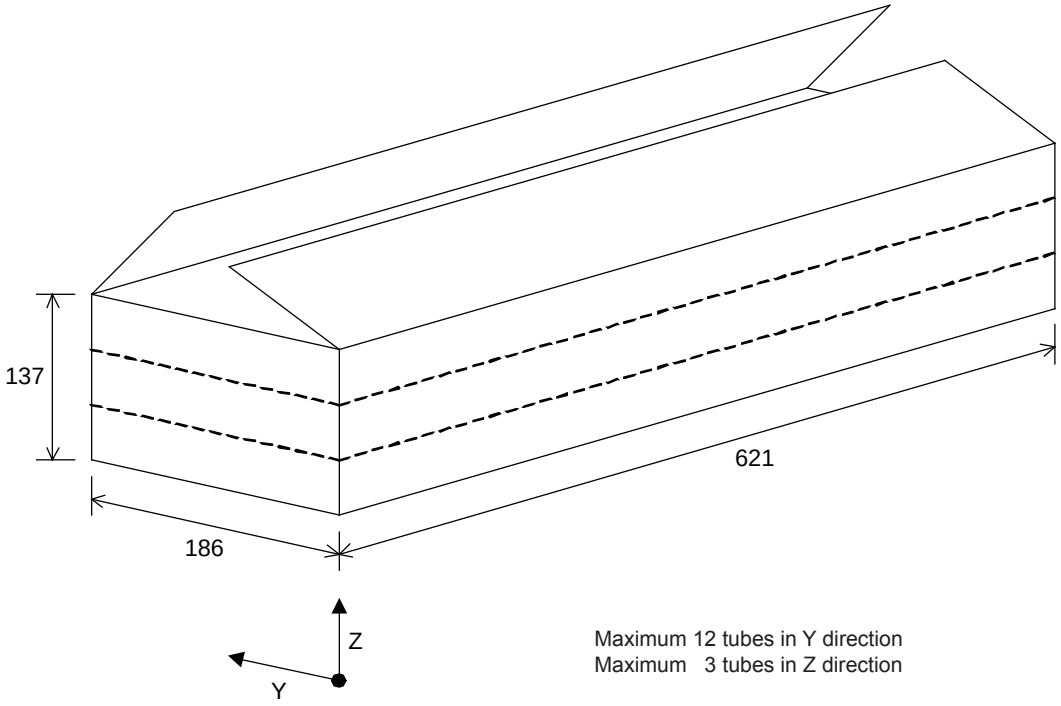
Packing Specification

Leadform 2171

Dimensions in millimeters



Tube material: PVC
Maximum 18 pieces per tube
(pins aligned along X direction)
Rubber plug each end



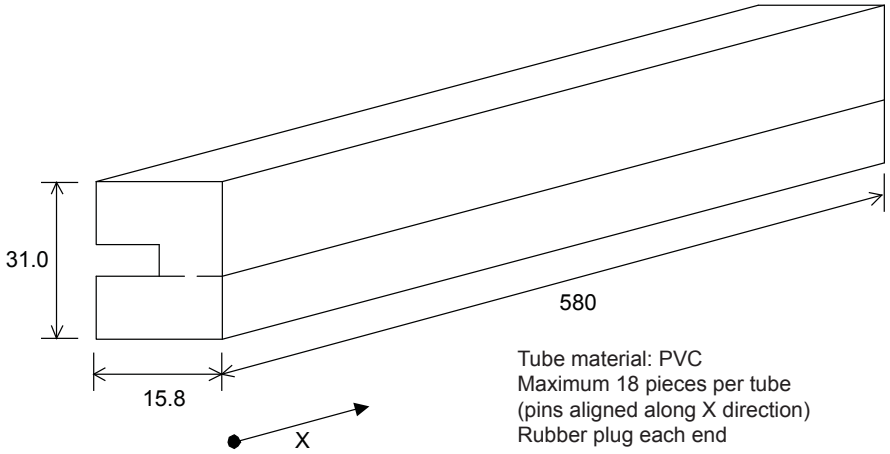
Maximum 12 tubes in Y direction
Maximum 3 tubes in Z direction

Maximum pieces per carton:
18 pieces per tube
12 tubes per layer
x 3 layers of tubes
648 pieces per carton

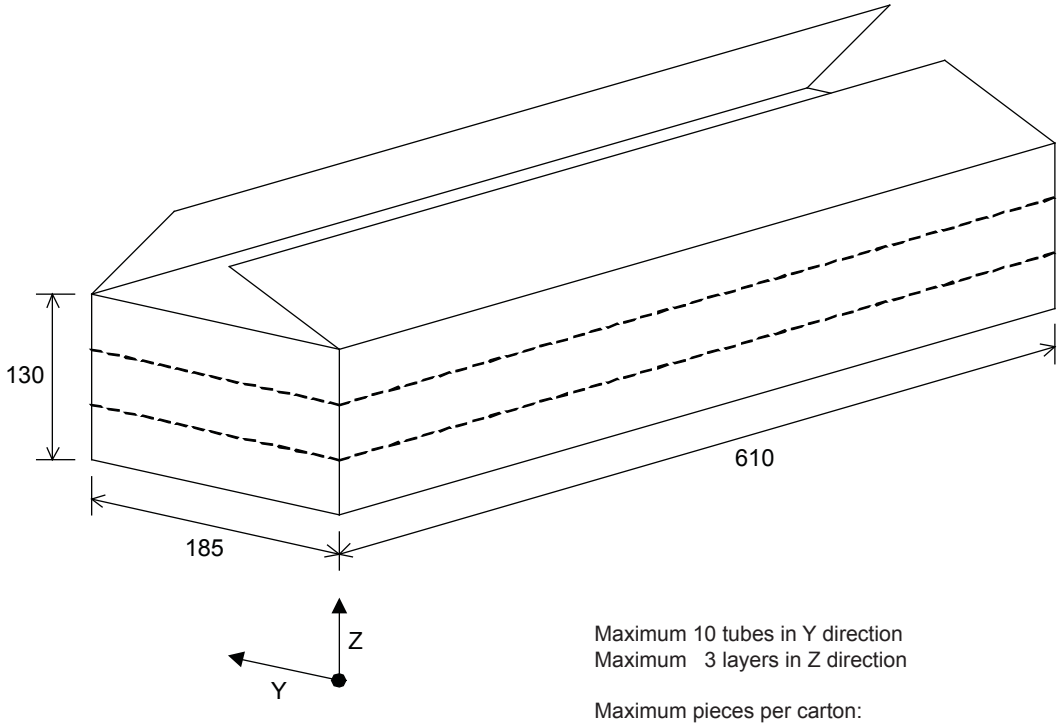
Packing Specification

Leadform 2175

Dimensions in millimeters



Tube material: PVC
Maximum 18 pieces per tube
(pins aligned along X direction)
Rubber plug each end



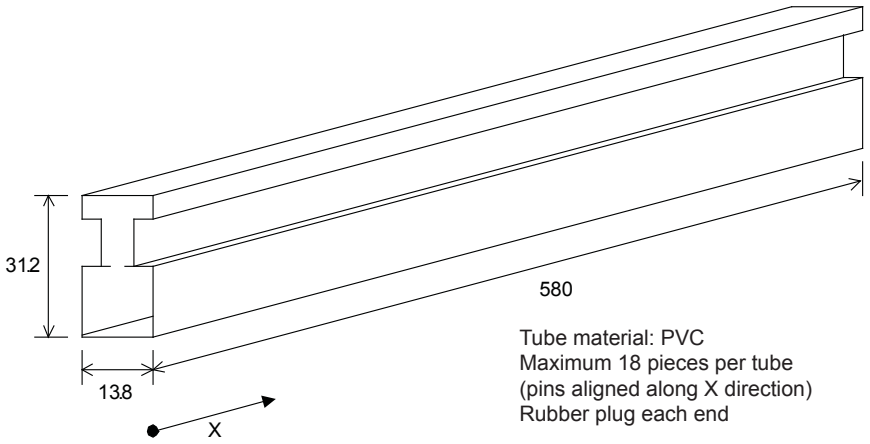
Maximum 10 tubes in Y direction
Maximum 3 layers in Z direction

Maximum pieces per carton:
18 pieces per tube
10 tubes per layer
x 3 layers of tubes
540 pieces per carton

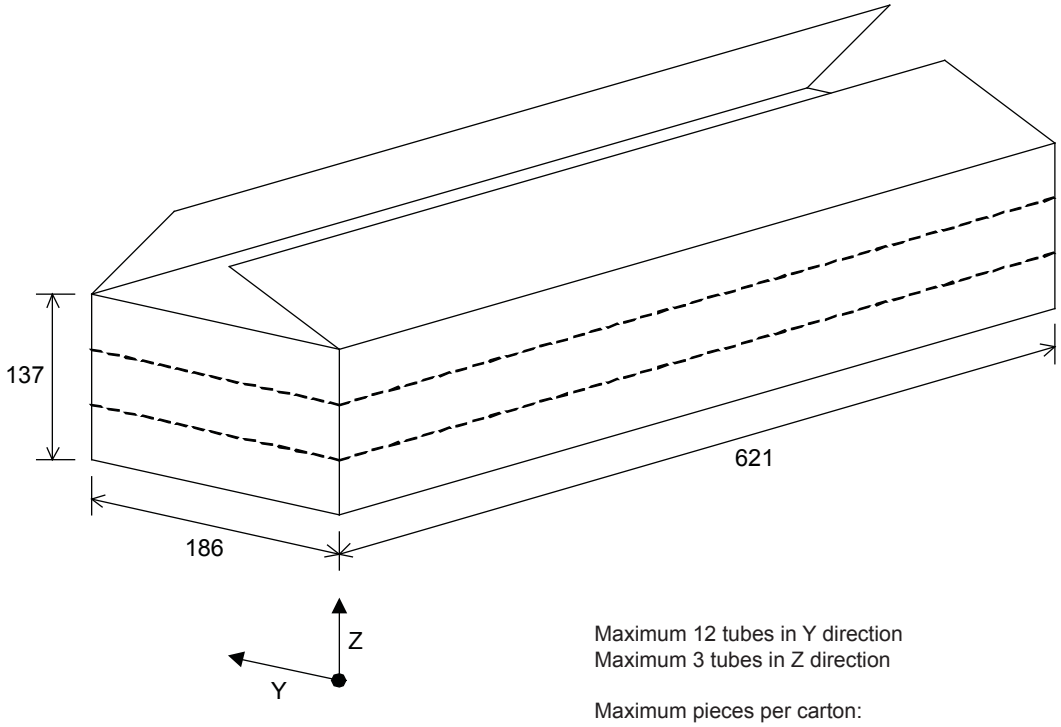
Packing Specification

Leadform 2178

Dimensions in millimeters

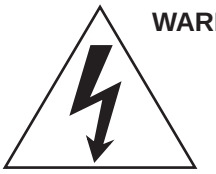


Tube material: PVC
Maximum 18 pieces per tube
(pins aligned along X direction)
Rubber plug each end



Maximum 12 tubes in Y direction
Maximum 3 tubes in Z direction

Maximum pieces per carton:
18 pieces per tube
12 tubes per layer
x 3 layers of tubes
648 pieces per carton



WARNING — These devices are designed to be operated at lethal voltages and energy levels. Circuit designs that embody these components must conform with applicable safety requirements. Precautions must be taken to prevent accidental contact with power-line potentials. Do not connect grounded test equipment.

The use of an isolation transformer is recommended during circuit development and breadboarding.

Because reliability can be affected adversely by improper storage environments and handling methods, please observe the following cautions.

Cautions for Storage

- Ensure that storage conditions comply with the standard temperature (5°C to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of products that have been stored for a long time.

Cautions for Testing and Handling

When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing device, shorts between adjacent products, and shorts to the heatsink.

Remarks About Using Silicone Grease with a Heatsink

- When silicone grease is used in mounting this product on a heatsink, it shall be applied evenly and thinly. If more silicone grease than required is applied, it may produce stress.
- Volatile-type silicone greases may permeate the product and produce cracks after long periods of time, resulting in reduced heat radiation effect, and possibly shortening the lifetime of the product.
- Our recommended silicone greases for heat radiation purposes, which will not cause any adverse effect on the product life, are indicated below:

Type	Suppliers
G746	Shin-Etsu Chemical Co., Ltd.
YG6260	Momentive Performance Materials, Inc.
SC102	Dow Corning Toray Silicone Co., Ltd.

Heatsink Mounting Method

Torque When Tightening Mounting Screws. The recommended tightening torque for this product package type is: 58.8 to 78.4 N•cm (6.0 to 8.0 kgf•cm).

Soldering

- When soldering the products, please be sure to minimize the working time, within the following limits:

  260±5°C 10 s

  380±5°C 5 s

- Soldering iron should be at a distance of at least 1.5 mm from the body of the products

Electrostatic Discharge

- When handling the products, operator must be grounded. Grounded wrist straps worn should have at least 1 MΩ of resistance to ground to prevent shock hazard.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of soldering irons or the solder bath must be grounded in other to prevent leak voltages generated by them from being applied to the products.
- The products should always be stored and transported in our shipping containers or conductive containers, or be wrapped in aluminum foil.

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